

IN THE SPECIFICATION

Please amend the specification, paragraph [0033], as follows:

[0033] In the present invention, one or more crosspieces or bridges 70 (FIG. 4) are formed between the ends 44 of the elongate interconnect slot 40. These crosspieces or bridges provide a multisegmented interconnect slot 40 and reinforce the interposer substrate 20 between the opposing edges 46 of the interconnect slot 40 at intermediate locations along the interconnect slot 40 against bending attributable to stresses applied thereto. Turning now to FIG. 4, one exemplary embodiment of the interposer substrate 20 of the invention is shown, together with a die 12 with a single central row 36 of bond pads 34. A crosspiece or bridge 70 comprises a filleted portion of the interposer substrate 20 which is left uncut during manufacture, i.e., two longitudinally adjacent interconnect slots or slot segments 40A, 40B are formed in interposer substrate 20 instead of a single interconnect slot, leaving crosspiece or bridge 70 in place. The interconnect slot segments 40A, 40B of the invention are shown with a combined length ($48A + 48B$) which is slightly less than the length 48 of a single prior art interconnect slot 40 for a similarly sized interposer substrate and may be about 67% or more of the length of the substrate. However, the longitudinal distal end-to-distal end length of the two interconnect slot segments 40A, 40B (or, with reference to FIG. 9A, three interconnect slot segments 40A, 40B and 40C) may be equivalent to, or even longer than, that of a single prior art interconnect slot 40, about 70 to 80% of the length of the substrate. The width 76 of the crosspiece or bridge 70 in the direction of centerline 42 is small, generally about 0.5 mm or more for a BT resin interposer substrate given manufacturing tolerances, but sufficient to extend between longitudinally adjacent bond pads 34. It may be desirable to space bond pads 34 into two or more longitudinally adjacent groups with increased pitch between groups to enable the use of larger-width crosspieces or bridges 70, as depicted in FIG. 9. If necessary, more than one crosspiece 70 may be used, generally evenly spaced along the interconnect slot 40 (see slot segments 40A, 40B and 40C in FIG. 9A), to divide the interconnect slot 40 into three or even more segments to provide a required resistance to bending. Generally, however, for bond pad row

lengths 84 for dice of about 3 to 15 mm in length, a single, substantially centrally placed crosspiece or bridge 70 is sufficient to avoid stress cracking or delamination of the wire bond mold cap 56. For longer dice, two or more longitudinally spaced crosspieces or bridges 70 may be desirable to avoid stress cracking or delamination of the wire bond mold cap 56.